

<b>PCN Number:</b>	20220802001.1	<b>PCN Date:</b>	August 03, 2022
<b>Title:</b>	Qualification of CFAB as an additional Fab site option for select LBC4 devices		
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Dept:</b>	Quality Services
<b>Proposed 1<sup>st</sup> Ship Date:</b>	Nov 3, 2022	<b>Sample requests accepted until:</b>	Sep 3, 2022*

**\*Sample requests received after September 3, 2022 will not be supported.**

**Change Type:**

<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>	Wafer Fab Site	<input checked="" type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process
		<input type="checkbox"/>	Part number change		

**PCN Details**

**Description of Change:**

Texas Instruments is pleased to announce the qualification of its CFAB fabrication facility as an additional Wafer Fab option for the devices listed in the "Product Affected" section.

Current Fab Site			New Fab Site		
Fab Site	Process	Wafer Diameter	Fab Site	Process	Wafer Diameter
DL-LIN	LBC4	150 mm	CFAB	LBC4	200 mm
DL-LIN	LBC4	200 mm			

Qual details are provided in the Qual Data Section.

**Reason for Change:**

These changes are part of our multiyear plan to transition products from our 150-millimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

**Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):**

None

**Changes to product identification resulting from this PCN:**

**Fab Site Information:**

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
DL-LIN	DLN	USA	Dallas
<b>CFAB</b>	<b>CU3</b>	<b>CHN</b>	<b>Chengdu</b>

Sample product shipping label (not actual product label):

TEXAS INSTRUMENTS  
 MADE IN: Malaysia  
 2DC: 20:  
 MSL 2 /260C/1 YEAR SEAL DT  
 MSL 1 /235C/UNLIM 03/29/04  
 OPT:  
 ITEM: 39  
 LBL: 5A (L)T0:1750

(1P) SN74LS07NSR  
 (Q) 2000 (D) 0336  
 (31T) LOT: 3959047MLA  
 (4W) TKY (1T) 7523483SI2  
 (P)  
 (2P) REV: (V) 0099917  
 (20L) CSO: SHE (21L) CCO:USA  
 (22L) ASO: MLA (23L) ACO: MYS

**Product Affected:**

BQ30420DBT	BQ3055DBTR	BQ30Z55DBTR-R3	BQ8050DBTR-D1
BQ30420DBTR	BQ30695ADBTR	BQ30Z55DBTR-R4	BQ8055ADBTR

BQ30422DBT	BQ30695ADBTR	BQ30Z55DBTR-V100	BQ8055ADBTR
BQ30422DBTR	BQ30Z50DBT	BQ30Z55DBTR-V100R2	BQ8055DBT
BQ30423DBT	BQ30Z50DBTR	BQ30Z55DBTR-V400	BQ8055DBTR
BQ30423DBTR	BQ30Z552DBTR	BQ30Z55DBT-V100R2	SN8765DBT
BQ30423DBT-R1	BQ30Z554DBT	BQ30Z55DBT-V400	SN8765DBTR
BQ30423DBTR-R1	BQ30Z554DBTR	BQ8050ADBTR	XTR300AIRGWR
BQ30472DBT	BQ30Z554DBT-R1	BQ8050ADBTR	XTR300AIRGWT
BQ30472DBTR	BQ30Z554DBTR-R1	BQ8050DBT	XTR305IRGWR
BQ3050DBT	BQ30Z55DBT-R3	BQ8050DBT-D1	XTR305IRGWT
BQ3050DBTR	BQ30Z55DBT-R4	BQ8050DBTR	

For alternate parts with similar or improved performance, please visit the product page on [TI.com](http://TI.com)

## Qualification Report

Approve Date 18-May-2022

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: BQ30420DBTR	QBS Process Reference: TLC5970RHPR	QBS Package Reference: BQ8015DBT
HTOL	Life Test, 125C	1000 Hours	-	3/231/0	-
HTSL	High Temp Storage Bake 170C	420 Hours	-	3/231/0	3/231/0
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/231/0	3/120/0
AC	Autoclave 121C	96 Hours	-	3/231/0	3/231/0
TC	Temperature Cycle, -65/150C	500 Cycles	-	3/231/0	3/231/0
HBM	ESD - HBM	1500 V	1/3/0	-	-
HBM	ESD - HBM	2000 V	-	3/9/0	-
CDM	ESD - CDM	1500 V	1/3/0	-	-
CDM	ESD - CDM	500 V	-	3/9/0	-
LU	Latch-up	(per JESD78)	1/6/0	3/18/0	-
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	1/30/0	-
MQ	Assembly MQ	Per Site Specifications	Pass	Pass	Pass

- QBS: Qual By Similarity

- Qual Device BQ30420DBTR is qualified at LEVEL2-260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- LU passed according to AEC Q100 Rev H Immunity Level B

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

**Green/Pb-free Status:**

Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the contact shown below or your local Field Sales Representative.

Location	E-Mail
WW Change Management Team	<a href="mailto:PCN_ww_admin_team@list.ti.com">PCN_ww_admin_team@list.ti.com</a>

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TI Information - Selective Disclosure

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